

FEATURES

IF Subsystem

Bandpass $\Sigma\Delta$ Modulator

Variable-Gain Preamplifier with 13 dB of AGC Range

Mixer

AGC Detector

Op Amp for LNA Biasing

ECL-to-CMOS Level Translator

Ultralow Power Design

2.7 V Operating Voltage

4.8 mA Current Consumption

Power-Down Control

Small 20-Lead SSOP Package

APPLICATIONS

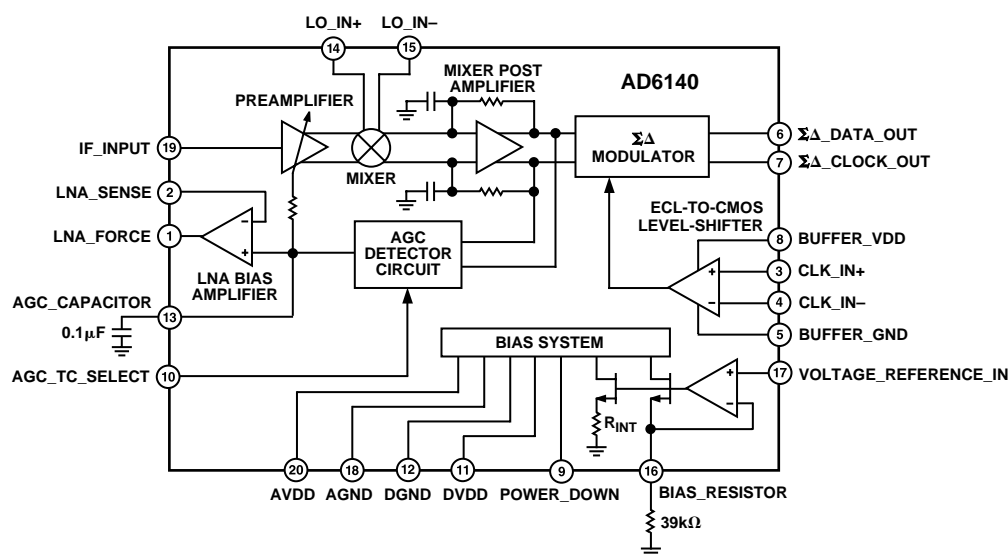
FLEX™, ReFLEX™ Receivers

Multimode Receivers

GENERAL DESCRIPTION

The AD6140 is a bandpass $\Sigma\Delta$ ADC IF IC for receivers requiring a high dynamic range and multiple filter bandwidths. With an external decimation filter, it creates a multibit analog-to-digital converter. The AD6140 consists of a variable gain, low noise preamplifier, mixer, AGC detector, bandpass $\Sigma\Delta$ modulator, an ECL-to-CMOS level translator for the system clock, and an auxiliary amplifier for use in biasing a discrete LNA. It is designed to operate with Motorola's ReFLEX chipset solution. Contact Motorola directly for more information about the ReFLEX chipset solution. With data and clock outputs at CMOS logic levels, it interfaces to an external decimation filter. It comes in a 20-lead plastic SSOP and operates over the -40°C to $+85^{\circ}\text{C}$ industrial temperature range at 2.7 V.

FUNCTIONAL BLOCK DIAGRAM



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AD6140—SPECIFICATIONS (T_A = +25°C, V_{CC} = 2.7 V, VOLTAGE_REFERENCE_IN = 1 V, unless otherwise noted)

Specification	Conditions	Min	Typ	Max	Units
OVERALL	VOLTAGE_REFERENCE_IN = 1 V ± 5% dc, IF = 49.6 MHz LO = 49.792 MHz or 49.408 MHz, 200 mV p-p Differential Input Clock = 6.144 MHz, 800 mV p-p Differential ECL Input, Clock Asymmetry = 50 ± 2.5%				
Input Third Order Intercept Point	At Max Gain	−27	−19		dBm
Noise Figure	At Max Gain, External Termination		10.5		dB
Input Resistance	At IF_INPUT (Pin 19)		2.5		kΩ
Input Capacitance	At IF_INPUT (Pin 19)		12		pF
Dynamic Range	6.25 kHz Bandwidth Centered at 192 kHz	76	83		dB
Maximum Gain			29.5		dB
Minimum Gain			16		dB
AGC DETECTOR					
AGC Threshold			−24		dBm
Capacitor Charging Current	AGC_TC_SELECT Input = Logic LOW (FAST AGC)		2.8		μA
	AGC_TC_SELECT Input = Logic HIGH (SLOW AGC)		50		nA
ECL-TO-CMOS LEVEL TRANSLATOR	VDD (to VDD − 0.8 V) Differential Levels				
Clock Output Drive	5 pF Load	2.6			V p-p
Clock Asymmetry	5 pF Load		±2.5		%
LNA BIAS AMPLIFIER VOLTAGE					
LNA_FORCE	2.9 V LNA_SENSE, Minimum Gain	1.7			V
LNA_SENSE Input Voltage Range		VDD		VDD − 0.3	V
POWER-DOWN INTERFACE					
Logic Threshold			0.7		V
Turn-On Response Time	To Valid Data Output		100		μs
Turn-Off Response Time	To Typical Power-Down Supply Current		100		μs
POWER SUPPLY					
Supply Voltage		2.5		2.9	V
Supply Current	Power-Down Input: Logic LOW = ON, IF_Input = 0 V		4.8	5.75	mA
Power-Down Current	Power-Down Input: Logic HIGH = OFF		3		μA
Operating Temperature Range		−40		+85	°C

Specifications subject to change without notice.

ABSOLUTE MAXIMUM RATINGS¹

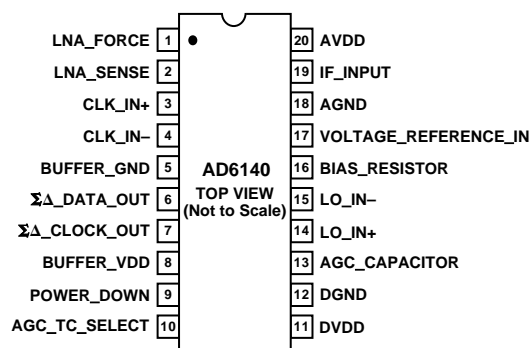
Supply Voltage to Ground +5.5 V
 Internal Power Dissipation² 50 mW
 Operating Temperature Range -40°C to +85°C
 Storage Temperature Range -65°C to +150°C
 Lead Temperature, Soldering (60 sec) +300°C

NOTES

¹Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended rating conditions for extended periods may affect device reliability.

²Thermal Characteristics:

20-Lead SSOP: $\theta_{JA} = 126^{\circ}\text{C}/\text{W}$.

PIN CONFIGURATION**ORDERING GUIDE**

Model	Temperature Range	Package Description	Package Option
AD6140ARS	-40°C to +85°C	Shrink Small Outline Package	RS-20
AD6140ARSRL	-40°C to +85°C	20-Lead Plastic SSOP on Tape-and-Reel	

CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the AD6140 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



PIN FUNCTION DESCRIPTION

Pin No	Pin Name	Function	Applicable Signal Levels
1	LNA_FORCE	Output For Biasing Discrete LNA	Output Ranges from 0 V (LNA OFF) to 2.7 V
2	LNA_SENSE	Input For Biasing Discrete LNA	VDD to VDD – 0.3 V Input
3	CLK_IN+	Positive 6.144 MHz ADC Clock Input	800 mV p-p Differential Input VDD to VDD – 0.8 V Levels Direct Coupled into 1500 Ω Impedance
4	CLK_IN–	Negative 6.144 MHz ADC Clock Input	800 mV p-p Differential Input VDD to VDD – 0.8 V Levels Direct Coupled into 1500 Ω Impedance
5	BUFFER_GND	ECL-to-CMOS Level Translator Ground	Pin Connected to Ground
6	$\Sigma\Delta$ _DATA_OUT	$\Sigma\Delta$ ADC Serial Data Output	CMOS Logic Levels
7	$\Sigma\Delta$ _CLOCK_OUT	6.144 MHz ADC Clock Output	CMOS Logic Levels
8	BUFFER_VDD	ECL-to-CMOS Level Translator VDD	Digital Supply Input
9	POWER_DOWN	Turns IC Off and On	CMOS Logic Levels; 0 V = ON, VPOS = OFF
10	AGC_TC_SELECT	AGC Time Constant Select; Changes AGC Capacitor Charging Current by 56:1, where FAST AGC Current is 56 \times SLOW AGC Current	CMOS Logic Levels; 0 V = Fast Mode, VPOS = Slow Mode
11	DVDD	Digital Power Supply Input	Pin Connected to Digital Supply
12	DGND	Digital Ground	Pin Connected to Ground
13	AGC_CAPACITOR	Charge/Discharge Current into AGC Integrator Capacitor	AGC Integration Capacitor Connected to Ground
14	LO_IN+	Positive LO Input	200 mV p-p Differential Input; Internally AC-Coupled into 1500 Ω Impedance
15	LO_IN–	Negative LO Input	200 mV p-p Differential Input, Internally AC-Coupled into 1500 Ω Impedance
16	BIAS_RESISTOR	Resistor to Ground Sets Overall Bias Current and Power Consumption	39 k Ω Resistor Connected to Ground
17	VOLTAGE_REFERENCE_IN	ADC Voltage Reference Input	Regulated and Filtered 1.0 V \pm 5% Input
18	AGND	Analog Ground	Pin Connected to Ground
19	IF_INPUT	IF Input	Typically 16.4 μ V p-p to 65.2 mV p-p
20	AVDD	Analog Power Supply Input	Pin Connected to Analog Supply

Typical Performance Characteristics—AD6140

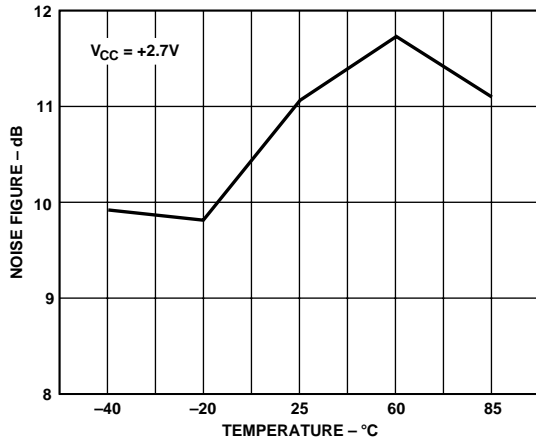


Figure 1. Noise Figure vs. Temperature

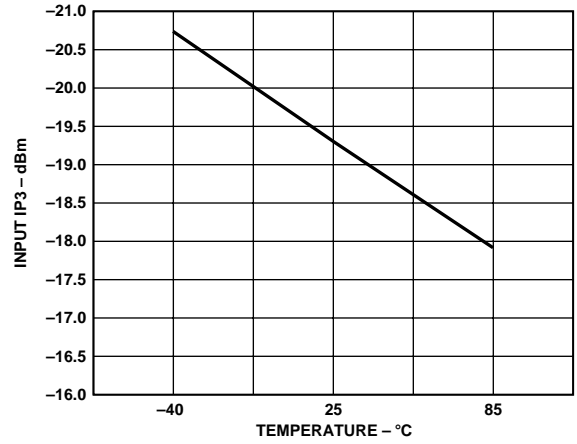


Figure 4. Input IP3 vs. Temperature

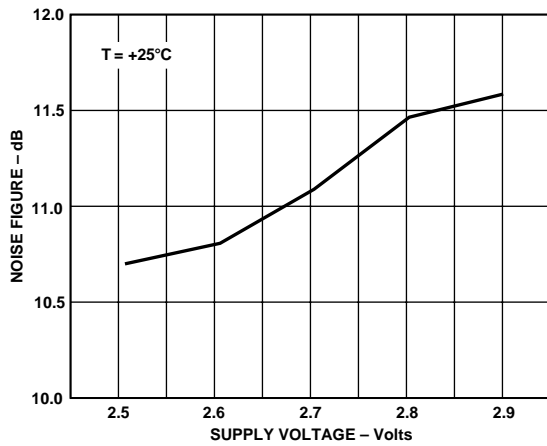


Figure 2. Noise Figure vs. Power Supply

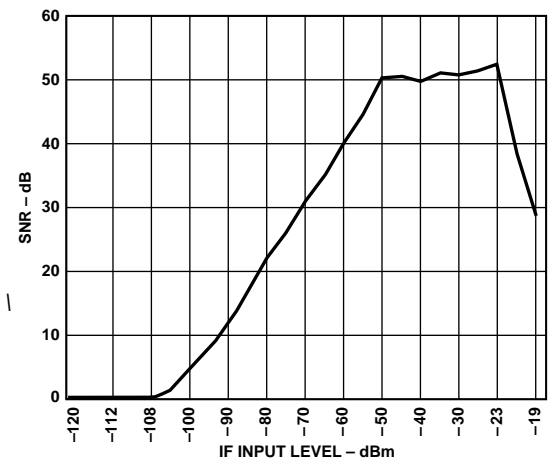


Figure 5. Signal to Noise Ratio vs. IF Input Level at $T_A = +25^\circ\text{C}$

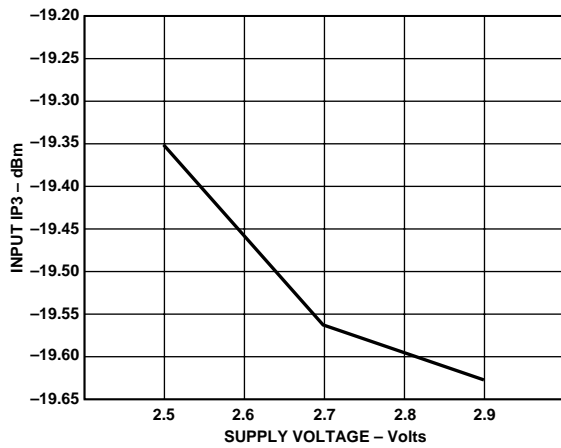


Figure 3. Input IP3 vs. Power Supply

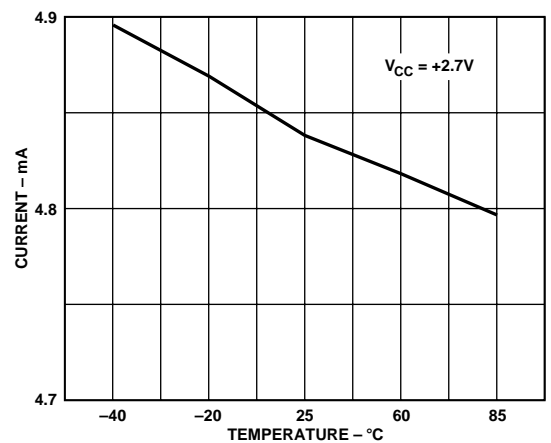


Figure 6. Supply Current vs. Temperature

AD6140

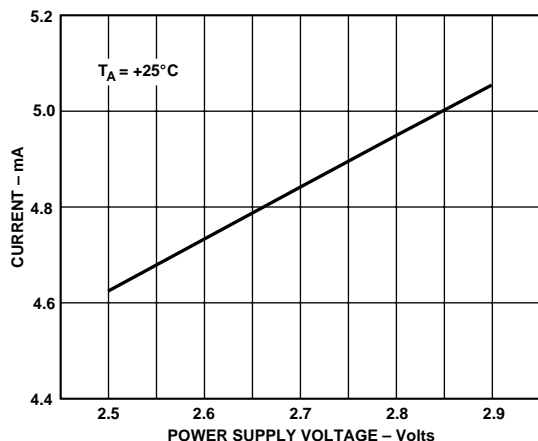


Figure 7. Supply Current vs. Power Supply Voltage

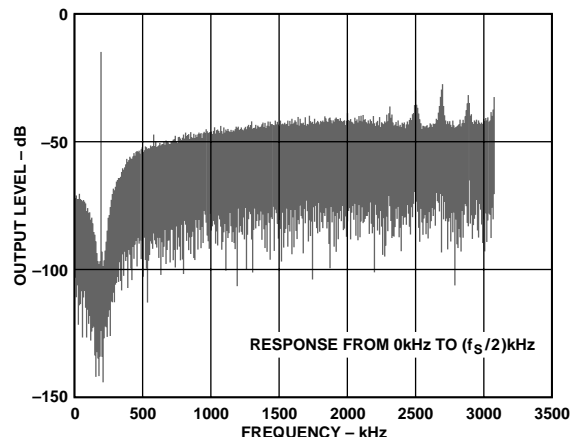


Figure 9. Output Spectrum of AD6140

ΣΔ MODULATION

A ΣΔ modulator uses feedback around a low noise quantizer (1 bit in this case) in order to “shape” the spectrum of quantization noise. Using this technique, we can shape noise away from an arbitrary passband, within which we can place a modulated signal. A ΣΔ modulator reproduces the input, but adds quantization noise, which can be digitally removed with a filter, known as a decimation filter. Applying this technique to bandpass signals results in an analog-to-digital converter suitable for converting the IF signals in a digital radio.

The output of the AD6140’s ΣΔ modulator is shown in Figure 9. As can be seen, the noise is shaped away from a narrow bandwidth, within which we place a signal (a sine wave in this case) resulting in a narrowband, high dynamic range digital representation of the analog input.

PRODUCT OVERVIEW

The AD6140 is a bandpass ΣΔ analog-to-digital converter IC for dual conversion receivers requiring a high dynamic range and multiple filter bandwidths. It consists of a variable gain, low noise preamplifier, mixer, automatic gain control (AGC) detector, bandpass ΣΔ modulator, an ECL to CMOS level translator and an auxiliary amplifier for use in biasing a discrete LNA.

The low noise preamplifier accepts a first IF input at 49.6 MHz from 16.4 μV p-p to 63.2 mV p-p. It provides a variable gain from 12 dB to 25 dB.

The mixer accepts an LO frequency of 49.792 MHz or 49.408 MHz, resulting in an IF frequency of 192 kHz. The LO level should be 200 mV p-p differential. It is ac-coupled to the AD6140. The mixer operates in the linear region, hence the gain of the mixer is a function of the LO level. As a result, special care must be taken to ensure that the LO level is 200 mV p-p,

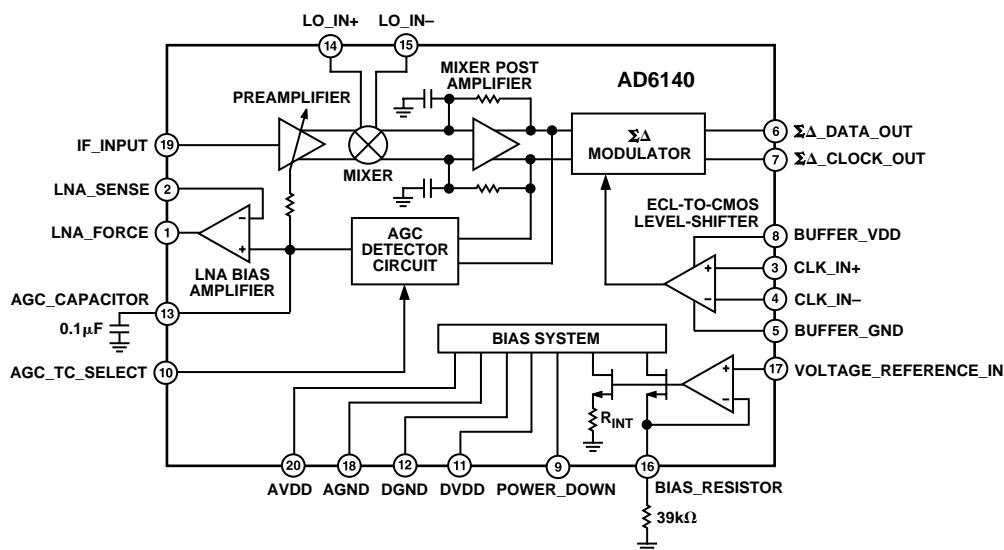


Figure 8. Functional Block Diagram

otherwise, the expected gain will not be obtained from the AD6140. In addition to the mixer, there is a mixer post-amplifier within the AD6140. The total gain from the mixer and mixer post-amplifier is 5 dB.

The $\Sigma\Delta$ modulator uses a 6.144 MHz clock, which is a differential ECL input. There is an ECL-to-CMOS converter on the AD6140, which converts this differential ECL input into a single-ended CMOS signal. This 6.144 MHz single-ended CMOS clock is provided at Pin 7 ($\Sigma\Delta_CLOCK_OUT$). The output data of the AD6140 is a 6.144 MHz single bitstream at Pin 6 ($\Sigma\Delta_DATA_OUT$). The signal gain through the $\Sigma\Delta$ modulator is -0.77 dB.

Within the $\Sigma\Delta$ modulator, the data output digital bitstream is fed through a 1-bit D/A converter and is fed back to numerous internal points. The level of this feedback signal, known as the full-scale level, defines the $\Sigma\Delta$ modulator input signal level, which would result in the output digital bitstream containing the maximum number of ones possible. This condition, known as maximum ones density, represents the maximum in-band output signal power of the $\Sigma\Delta$ modulator. The full-scale level is set to 2 V p-p or -4.77 dBm (relative to 1500 Ω). However, if a signal into the modulator is -4.77 dBm, the modulator will enter an unstable state. Consequently, the maximum input to the modulator is constrained to 5 dB less than the signal, which would produce maximum ones density. This level, defined as the clip level, is -9.77 dBm (relative to 1500 Ω).

The maximum signal into the modulator does not correspond to maximum ones density. The entire dynamic range of the resulting analog to digital converter ($\Sigma\Delta$ modulator plus decimation filter) is not realized. In order to relate the maximum signal into the modulator to the maximum signal out of the modulator, a gain of 5 dB should be applied in the decimation filter.

As can be seen in Figure 5, the output signal to noise ratio will increase until a point at which it rapidly degrades. This point represents the input signal level where the $\Sigma\Delta$ modulator has become unstable. As a result, the maximum input signal level is constrained by the point at which it is so high that instability occurs in the modulator. Dynamic range is defined as the difference between the integrated noise floor (within a particular bandwidth) and the power in the output signal just before the $\Sigma\Delta$ modulator has become unstable. For a typical 6.25 kHz bandwidth centered around 192 kHz, the AD6140 has 83 dB of dynamic range.

In order to increase the range of useful input signals of the AD6140, an AGC detector is employed which senses the input signal level to the $\Sigma\Delta$ modulator and adjusts the gain in the preamplifier. The AGC circuitry provides 13 dB of automatic gain control range. The AGC operates when the internal AGC voltage is between 700 mV (minimum gain) and 1.55 V (maximum gain). This voltage can be measured on the AGC_CAPACITOR pin (Pin 13).

The AD6140 can be configured with the chip powered up or down. In order to power the chip down, set pin POWER_DOWN (Pin 9) high. In order to power it up, set pin POWER_DOWN (Pin 9) low.

Finally, an auxiliary amplifier used for biasing an external discrete LNA is provided with the AD6140.

FREQUENCY PLAN

The AD6140 and its $\Sigma\Delta$ modulator are designed for a specific frequency plan: a 6.144 MHz master clock, a 49.6 MHz first IF input, and a 192 kHz center frequency in the bandpass $\Sigma\Delta$ modulator. The local oscillator may use high-side or low-side injection. The specifications for the AD6140 are only valid for this frequency plan. Any deviation from this frequency plan may result in degradation of the specified performance. Furthermore, there are only specific frequency plans which will result in acceptable performance for most applications. To avoid problems, do not change the frequency plan.

USING THE AD6140

In this section, we will examine a few areas of special importance and include a few general applications tips. As is true of any device operating in the IF frequency range, special care must be taken in PC board layout. The location of the particular grounding points must be considered, with the objective of minimizing any unwanted signal coupling. Specifically, care should be taken in the layout of the IF and LO signal paths as well as the data and clock digital bit-streams. Layout of these portions of the PC board require special attention in order to ensure that the high frequency portions of these signals do not couple into other signals in the system. In order to maintain balance in differential signal levels, be sure to keep short and equal length transmission lines.

The power supplies should be decoupled to ensure a clean dc signal. Special care should be taken with respect to ensuring that the BUFFER_VDD is especially clean and at the appropriate levels since the output in-band noise floor is particularly sensitive to this supply.

The IF input signal should be impedance matched and ac coupled. The impedance looking into the IF input pin is typically a 2.5 k Ω resistance in parallel with a 12 pF capacitance. The 1 V reference signal should be regulated and filtered.

The value of the BIAS_RESISTOR (Pin 16) is 39 k Ω . The bias resistor sets the current consumption of the AD6140. Because the AD6140 was characterized with a 39 k Ω bias resistor, this is the only value for which the AD6140 specifications are guaranteed. Maximum current consumption is measured when the AD6140 is operating at maximum gain.

The AGC integration capacitor should be large enough to bypass any externally-generated noise on the internal AGC line to ground in addition to providing a path for the charging and discharging of the AGC current. In the Motorola ReFLEX chipset solution, this capacitor is 0.1 μ F. The AGC time constant is switch-selectable with the AGC_TC_SELECT pin (Pin 10). The AGC time constant has a typical current ratio of 56:1 when in the fast mode relative to slow mode. The nominal AGC current in the fast (high current) position is 2.8 μ A and in the slow (low current) position is 50 nA. The AGC time constant may be calculated from Equation 1.

$$T = \frac{CV}{I} \quad (1)$$

where T is the AGC time constant in seconds, C is the value of the AGC capacitor in Farads, V is the full-scale change in the AGC voltage, and I is the charging current in amperes.

AD6140

LEVEL DIAGRAM

Figure 10 shows a simplified block diagram of the AD6140 with the expected signal levels for the minimum gain configuration.

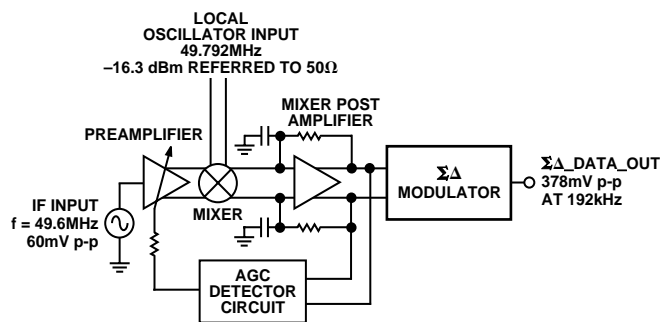


Figure 10. Level Diagram

Motorola ReFLEX Transceiver

Figure 11 shows a block diagram of the Motorola ReFLEX chipset solution including the AD6140. As can be seen, the AD6140 accepts an IF input from a crystal filter at 49.6 MHz. The frequency synthesizer provides the 6.144 MHz clock, while the LO is also generated from the frequency synthesizer but is fed to the AD6140 via the I/Q modulator. The IF data output and the clock output both feed into the IF data processor. The LNA bias amplifier provides the AGC voltage for the first LNA in the receive path. The dc power is supplied from the power management chip.

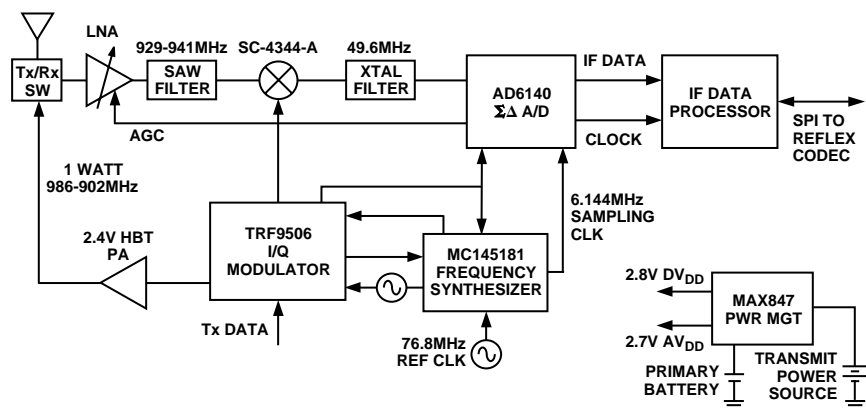


Figure 11. ReFLEX Transceiver Block Diagram

OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

20-Lead SSOP
(RS-20)

